



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Steven Towle

Title: POLYMERIC ENCAPSULATION MATERIAL WITH FIBROUS FILLER FOR USE IN MICROELECTRONIC CIRCUIT PACKAGING

Docket No. 884.415US1

Serial No.: 09/854,539

Filed: May 14, 2001

Due Date: October 25, 2002

Examiner: Marc Q. Kimenez

Group Art Unit: 3726

Commissioner for Patents  
Washington, D.C. 20231

**RECEIVED**

OCT 31 2002

We are transmitting herewith the following attached items (as indicated with an "X"):

A return postcard.  
 Response to Restriction Requirement (4 Pages).

TECHNOLOGY CENTER R3726

Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional required fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.  
P.O. Box 2938, Minneapolis, MN 55402 (612-373-6900)

By: Ann M. McCrackin  
Atty: Ann M. McCrackin  
Reg. No. 42,858

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231, on this 25 day of October, 2002.

Jane E. Brockschink  
Name

Jane E. Brockschink  
Signature

**Customer Number 21186**

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

P.O. Box 2938, Minneapolis, MN 55402 (612-373-6900)  
(GENERAL)



09/854,539

11/5/02  
*Patent*

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Steven Towle  
Serial No.: 09/854,539  
Filed: May 14, 2001  
Title: POLYMERIC ENCAPSULATION MATERIAL WITH FIBROUS FILLER FOR  
USE IN MICROELECTRONIC CIRCUIT PACKAGING

Examiner: Marc Q. Jimenez  
Group Art Unit: 3726  
Docket: 884.415US1

**RESPONSE TO RESTRICTION REQUIREMENT UNDER 37 C.F.R. § 1.142 AND**  
**PRELIMINARY AMENDMENT UNDER 37 C.F.R. § 1.115**

Commissioner for Patents  
Washington, D.C. 20231

In response to the Restriction Requirement mailed September 25, 2002, Applicant elects, *without* traverse, Group I (claims 1-17). Applicant cancels remaining claims 18-24 *without* prejudice or disclaimer, and reserves the right to reintroduce them in one or more divisional applications at a later date.

In response to the first alleged patently distinct species, Applicant elects, without traverse fibrous filler includes carbon fibers.

In response to the second alleged patently distinct species, Applicant elects, without traverse polymeric resin includes epoxy.

**RECEIVED**

OCT 3 1 2002

**IN THE CLAIMS**

Please add new claims 25-31.

TECHNOLOGY CENTER R370

25. (New) A microelectronic device comprising:  
a flexible circuit board including a first side and a second side;  
a microelectronic die attached to the first side;  
a compliant buffer on the first side of the flexible circuit board, wherein the compliant buffer is between the die and the flexible circuit board; and  
a fiber reinforced encapsulation material to hold the microelectronic die to the flexible circuit board.